

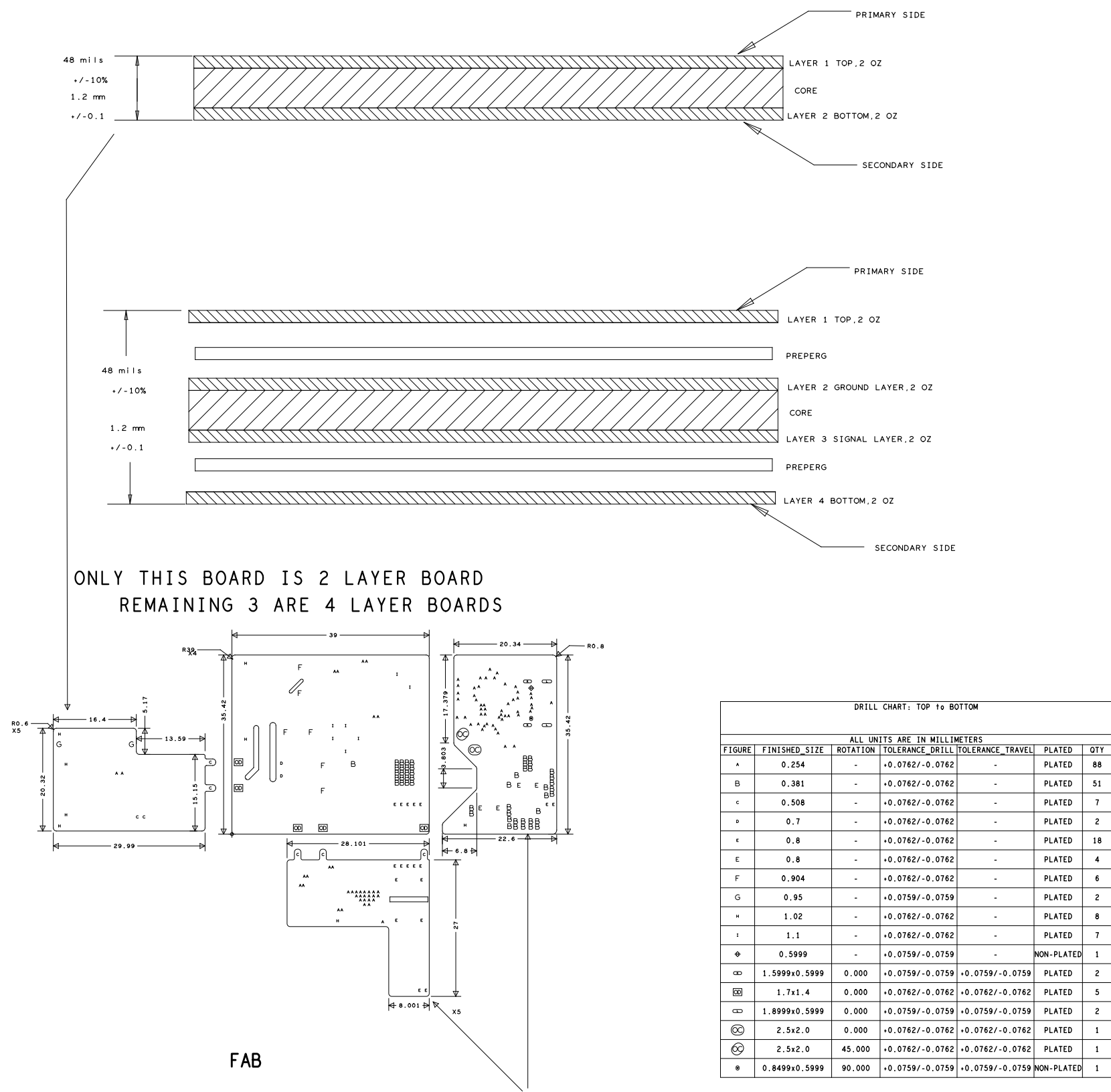
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	INITIAL RELEASE	02/09/20	RAAH
2	REVISION 2	04/01/21	HSUB
3	REVISION 3	12/03/21	HSUB


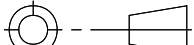
NOTES: ( UNLESS OTHERWISE SPECIFIED )

1. RoHS COMPLIANT MATERIALS DECLARATION REQUIRED.
2. MATERIAL:
  - A. FR4 OR EQUIVALENT MATERIAL(HIGH ELECTRONIC RELIABILITY) MUST CONFIRM TO UL94V-0
  - B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
  - C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
  - A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES  $\pm .003$  to 1. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
  - B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:

COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
  - A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
  - B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPLIANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
  - A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR \*BLUE\*\*
7. FINISH:
  - A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).
  - B. NICKEL THICKNESS: 100-200 MICROINCHES.
  - C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.

FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
  - A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
  - B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE  $\pm 10\%$  UNLESS OTHERWISE SPECIFIED.
12. ENSURE ALL THE VIA HOLES ARE FILLED WITH SOLDER MASK TO ENSURE GOOD QUALITY OF SILK SCREEN PRINT.
13. CARE MUST BE TAKEN TO AVOID OVER ETCHING OF COPPER ON PADS.
14. THIS IS HIGH VOLTAGE BOARD. SO DON'T ADD THIEVING COPPER IN VOID AREA FOR COPPER BALANCE.
15. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH CTI STANDARD OF  $400 < CTI < 600$



UNLESS OTHERWISE SPECIFIED		SIGNATURES		DATE		<div></div> <div>198 CHAMPION COURT SAN JOSE, CA 95134 (408) 943-2600</div>							
DIMENSIONS ARE IN INCHES TOLERANCES ON;      ANGLES +/- 2° 2 PL DECIMALS +/- .010 3 PL DECIMALS +/- .005 THIRD ANGLE PROJECTIONS 		DRAWN :      SAND		12/03/21									
<div>CYPRESS PROPRIETARY</div> <div>THIS DOCUMENT CONTAINS CONFIDENTIAL, PROPRIETARY INFORMATION THAT IS CYPRESS SEMICONDUCTOR PROPERTY. DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY CYPRESS.</div>		CHECKED :      HSUB		12/03/21		<div>FABRICATION DRAWING</div> <div>CY-SD1124A PAG1S+PAG1P</div> <div>45W SOLUTION DEMO BOARD</div>							
		ENGRG :      HSUB		12/03/21									
		ISSUED											
						SIZE		FSCM NO		DWG NO		REV	
						C				610-XXXXX-XX		03	
						SCALE: 1/1						SHEET: 1 OF 1	